

Electronic Patent Application Fee Transmittal

Application Number:	10612764			
Filing Date:	30-Jun-2003			
Title of Invention:	MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND PROCESS OF MAKING SAME			
First Named Inventor/Applicant Name:	Vassoudevane Lebonheur			
Filer:	Michael Mallie/In Chung			
Attorney Docket Number:	042390.P15858			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				1740